

Description

The AO3415 is the high cell density trenched P-ch MOSFETs, which provide excellent R_{DS(on)} and gate charge for most of the synchronous buck converter applications.

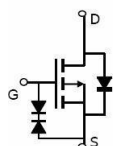
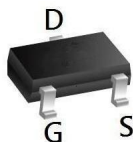
The AO3415 meet the RoHS and Green Product requirement with full function reliability approved.

Super Low Gate Charge

Green Device Available

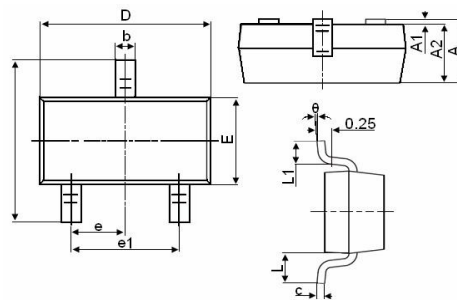
Excellent CdV/dt effect decline

Advanced high cell density Trench technology



Product Summary

BVDSS	R _{DS(on)}	I _D
-20V	28mΩ	-4.2A



Symbol	Dimensions in Millimeters	
	MIN.	MAX.
A	1.050	1.250
A1	0.000	0.100
A2	1.050	1.150
b	0.300	0.500
c	0.100	0.200
D	2.800	3.000
E	1.500	1.700
E1	2.650	2.950
e	0.950TYP	
e1	1.800	2.000
L	0.550REF	
L1	0.300	0.600
θ	0°	8°

Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	-20	V
V _{GS}	Gate-Source Voltage	±12	V
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ -4.5V ¹	-4.2	A
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ -4.5V ¹	-3.0	A
I _{DM}	Pulsed Drain Current ²	-16	A
P _D @T _A =25°C	Total Power Dissipation ³	1.31	W
P _D @T _A =70°C	Total Power Dissipation ³	0.84	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-Ambient ¹	---	125	°C/W
R _{θJA}	Thermal Resistance Junction-Ambient ¹ (t ≤ 10s)	---	---	°C/W

AO3415-3L

Electrical Characteristics (T_J=25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D = -250μA	-20	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -20V, V _{GS} =0V,	-	-	-1	μA
I _{GSS}	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} = ±12V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D = -250μA	-0.4	-0.7	-1.0	V
R _{DS(on)}	Static Drain-Source on-Resistance note2	V _{GS} = -4.5V, I _D = -4.1A	-	28	35	mΩ
		V _{GS} = -2.5V, I _D = -3A	-	38	53	
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} = -10V, V _{GS} =0V, f=1.0MHz	-	830	-	pF
C _{oss}	Output Capacitance		-	132	-	pF
C _{rss}	Reverse Transfer Capacitance		-	85	-	pF
Q _g	Total Gate Charge	V _{DS} = -10V, I _D = -2A, V _{GS} = -4.5V	-	8.8	-	nC
Q _{gs}	Gate-Source Charge		-	1.4	-	nC
Q _{gd}	Gate-Drain(“Miller”) Charge		-	1.9	-	nC
Switching Characteristics						
t _{d(on)}	Turn-on Delay Time	V _{DD} = -10V, I _D = -3.3A, R _G = 1Ω, V _{GEN} = -4.5V	-	10	-	ns
t _r	Turn-on Rise Time		-	32	-	ns
t _{d(off)}	Turn-off Delay Time		-	50	-	ns
t _f	Turn-off Fall Time		-	51	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	-5.0	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-16	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} =0V, I _S = -4.1A	-	-	-1.2	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width≤300μs, Duty Cycle≤2%

RATING AND CHARACTERISTIC CURVES (AO3415-3L)

Figure1: Output Characteristics

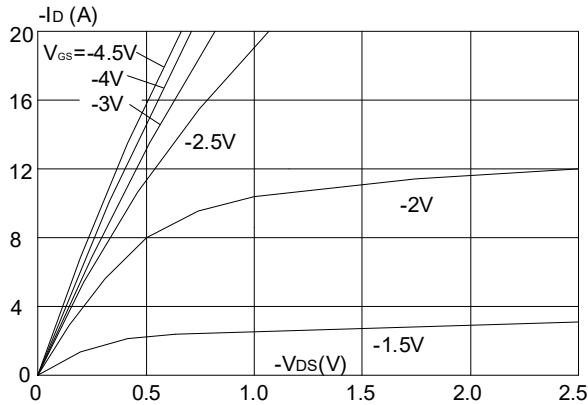


Figure 2: Typical Transfer Characteristics

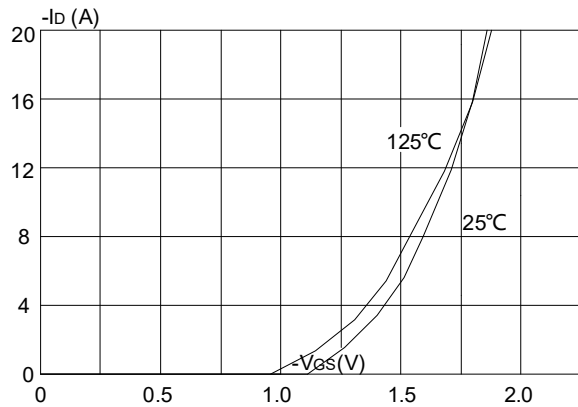


Figure 3: On-resistance vs. Drain Current

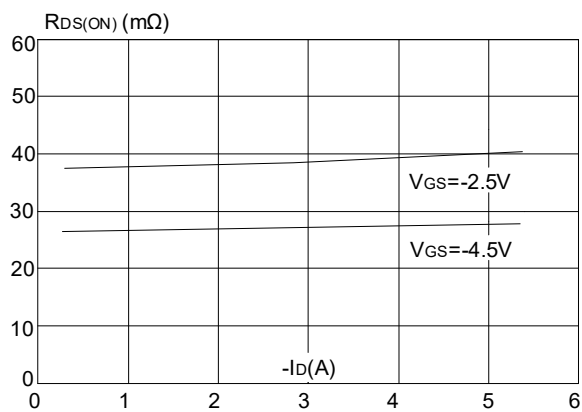


Figure 4: Body Diode Characteristics

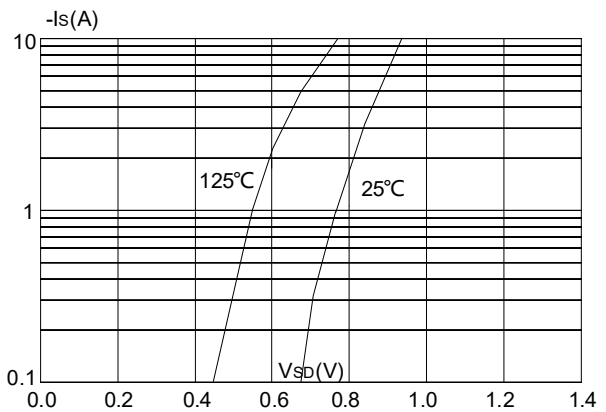


Figure 5: Gate Charge Characteristics

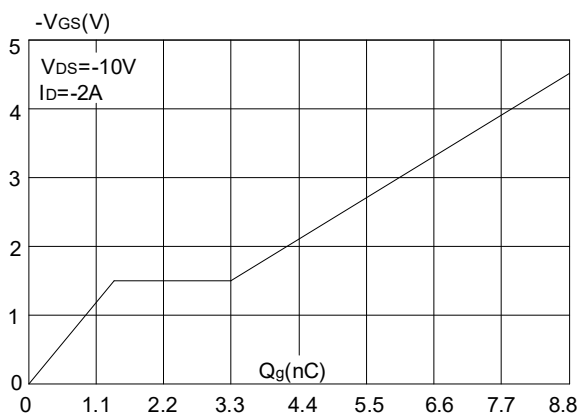
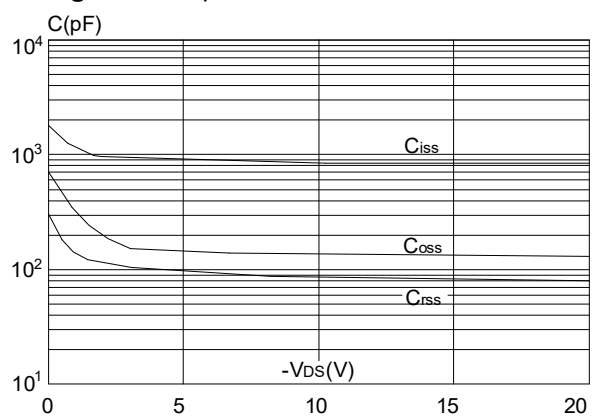


Figure 6: Capacitance Characteristics



RATING AND CHARACTERISTIC CURVES (AO3415-3L)

Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

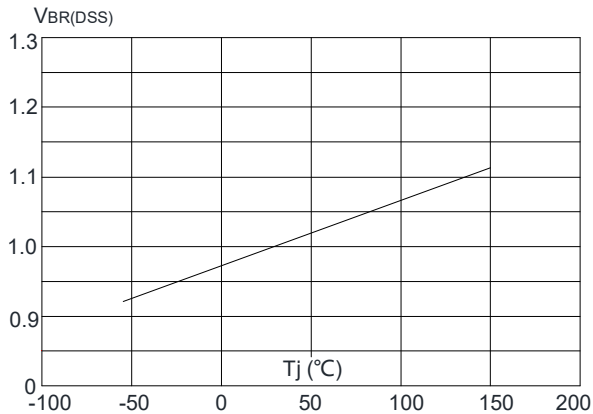


Figure 8: Normalized on Resistance vs. Junction Temperature

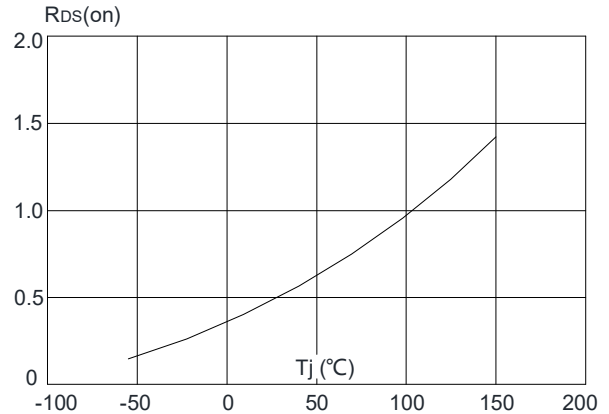


Figure 9: Maximum Safe Operating Area

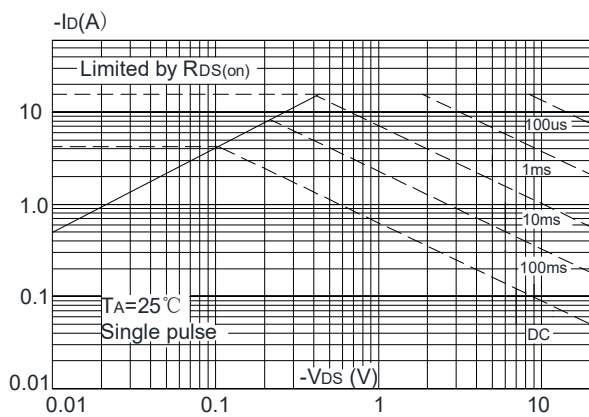


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

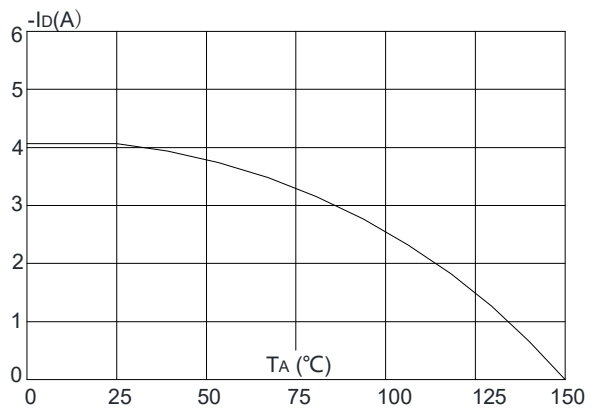


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

